

Abstract of the Disclosure:

A wafer chuck for semiconductor wafer manufacturing has a surface for the accommodation of a semiconductor wafer. The surface has a concave shape. The wafer, especially with a diameter of more than 300 mm, normally has a concave or convex warpage according to tensile strength from deposited layers.

5 By appropriate size of the concaveness of the chuck surface the perimeter edge of the wafer always touches the hot surface of the chuck first, so that the wafer is flattened, thereby avoiding a movement of the wafer on the hot chuck surface.

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